

Docket No.: 50090-308

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Akio UENISHI

Serial No.: 09/901,046

Filed: July 10, 2001

For: SEMICONDUCTOR DEVICE

Group Art Unit: 2811

Examiner: Quang D. Vu

AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

This Amendment is filed in response to the Office Action dated February 7, 2002.

IN THE SPECIFICATION:

Please insert the following paragraph on page 4 at line 19:

FIG. 6 is a sectional view showing a high heat conductor layer united with a terminal wiring.

Please replace the paragraph beginning at page 9, line 4, with the following rewritten paragraph:

Also, when the high heat conductor layer 6 is used in common with terminal wiring 4A and 4B made of Al or the like, since the area of the high heat conductor layer 6 can be increased by using the high heat conductor layer 6 as a part of the ground/power wiring region or input/output pads, the resistance to surge power of not only an extremely short